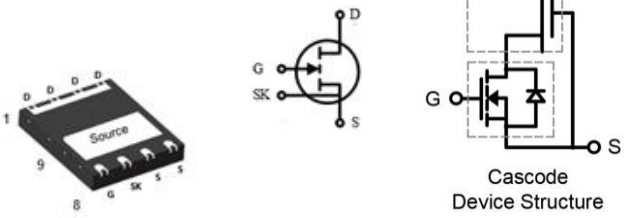
Features

- Easy to use, compatible with standard gate drivers
- Excellent Q_G x $R_{DS(on)}$ figure of merit (FOM)
- Low Q_{RR}, no free-wheeling diode required
- Low switching loss
- RoHS compliant and Halogen-free
- Qualified according to JEDEC criteria

Product Summary		
V_{DSS}	650	V
$R_{DS(on),\ typ}$	70	mΩ
$Q_{G,\ typ}$	12.5	nC
$Q_{RR,\ typ}$	77	nC



Applications

- High efficiency power supplies
- Telecom and datacom
- Automotive
- Servo motors

Packaging

Part Number	Marking	Package	Packaging	Base QTY
CRNLE070C65H	CRNLE070C65H	DFN8X8-8	Tape and Reel	2500

Maximum ratings, at T_C=25 ° C, unless otherwise specified

Symbol	Parameter		Limit Value	Unit
I_D	Continuous drain current @TC=25° C		24	A
	Continuous drain current @TC=100° C		15	A
I_{DM}	Pulsed drain current @TC=25° C (pulse width: 100us)		107	A
	Pulsed drain current @TC=150° C (pulse width: 100us)		82	A
V_{DSS}	Drain to source voltage (TJ = -55° C to 150° C)		650	V
V_{TDSS}	Transient drain to source voltage a		800	V
V_{GSS}	Gate to source voltage		±20	V
P_D	Maximum power dissipation @TC=25° C		74	W
T_C	Operating temperature	Case	-55 to 150	° C
T_J		Junction	-55 to 150	° C
T_S	Storage temperature		-55 to 150	° C
T_{CSOLD}	Soldering peak temperature		260	° C

Thermal Resistance

Symbol	Parameter	Typical	Unit
$R_{\Theta JC}$	Junction-to-case	1.7	°C/W
$R_{\Theta JA}$	Junction-to-ambient [b]	50	°C/W

Notes:
a. Off-state spike duty cycle < 0.01, spike duration < 2us
b. Device on one layer epoxy PCB for drain connection (vertical and without air stream cooling, with 6cm^{2}copper area and 70μm thickness)

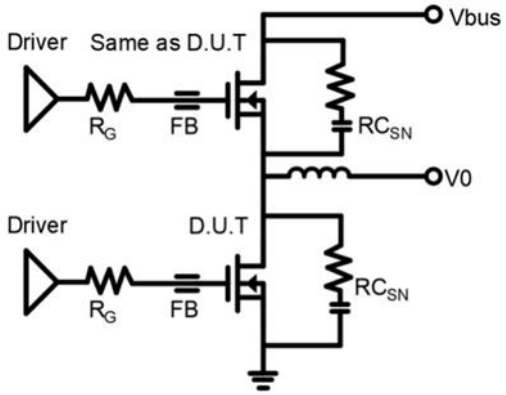
Electrical Parameters, at T_J=25°C, unless otherwise specified

Symbol	Min	Typ	Max	Unit	Test Conditions
Forward Characteristics					
$V_{DSS-MAX}$	650	-	-	V	V_{GS}=0V
BV_{DSS}	-	1000	-		V_{GS}=0V, I_{DSS}=250μA
$V_{GS(th)}$	3	4	5	V	V_{DS}=V_{GS}, ID=500μA
$R_{DS(on)}$ [c]	-	70	90	mΩ	V_{GS}=12V, I_D=4A, T_J=25°C
	-	140	-		V_{GS}=12V, I_D=4A, T_J=150°C
I_{DSS}	-	8	20	μA	V_{DS}=700V, V_{GS}=0V, T_J=25°C
	-	50	-	μA	V_{DS}=700V, V_{GS}=0V, T_J=150°C
I_{GSS}	-	-	150	nA	V_{GS}=20V
	-	-	-150	nA	V_{GS}=-20V
C_{ISS}	-	543	-	pF	V_{GS}=0V, V_{DS}=400V, f=1MHz
C_{OSS}	-	71	-	pF	
C_{RSS}	-	2.9	-	pF	
$C_{O(er)}$	-	101	-	pF	V_{GS}=0V, V_{DS}=0 - 400V
$C_{O(tr)}$	-	193	-	pF	
Q_{OSS}	-	77	-	nC	
Q_G	-	12.5	-	nC	V_{DS}=400V, V_{GS}=0 - 12V, I_D=14A
Q_{GS}	-	2.5	-		
Q_{GD}	-	4.5	-		
$t_{D(on)}$	-	30	-		V_{DS}=400V, V_{GS}=0 - 12V, I_D=14A, R_G=47Ω
t_R	-	16	-		
$t_{D(off)}$	-	80	-		
t_F	-	10	-		
Reverse Characteristics					
V_{SD}	-	1.2	-	V	V_{GS}=0V, I_S=7A, T_J=25°C
	-	1.5	-		V_{GS}=0V, I_S=14A, T_J=25°C
	-	2	-		V_{GS}=0V, I_S=14A, T_J=150°C
t_{RR}	-	33	-	ns	I_S=14A, V_{GS}=0V, d_i/d_t=1000A/us, V_{DD}=400V
Q_{RR}	-	77	-	nC	

Notes:
c. Dynamic on-resistance; see Figure 19 and 20 for test circuit and configurations

Circuit Implementation

(1) Mostly used in half bridge and full bridge topology



Recommended Half-bridge Circuit

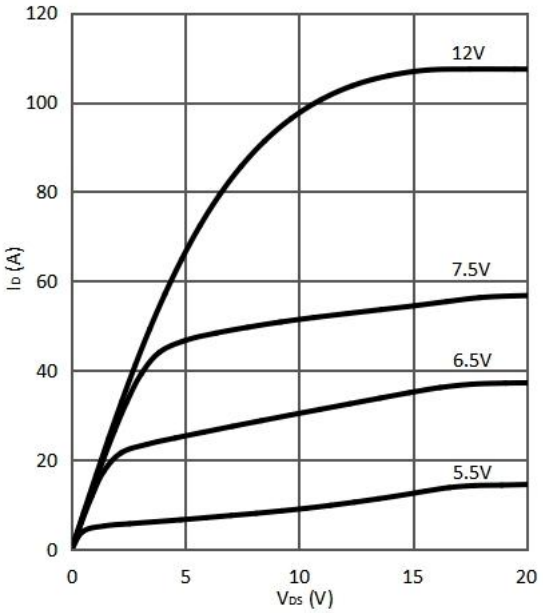
Recommended gate drive: (0 V, 8 V) with $R_{G(tot)}$ = 40 Ω, where $R_{G(tot)} = R_G + R_{driver}$

Gate Ferrite Bead (FB)	Gate Resistance (R_G)	RC Snubber (RC_{SN})
MPZ1608S471ATA00	33 Ω	69 pF + 15 Ω

Notes:
d. RC_{SN} should be placed as close as possible to the drain pin
e. The layout and wiring of the drive circuit should be as short as possible

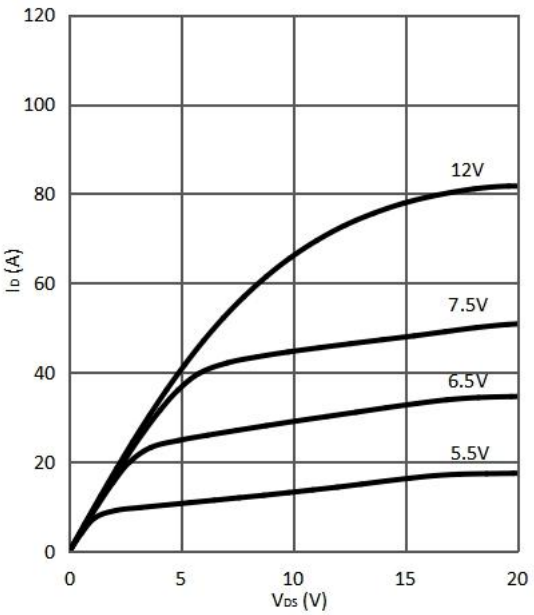
Typical Characteristics, at T_C=25 ° C, unless otherwise specified

Figure 1. Typical Output Characteristics T_J=25° C



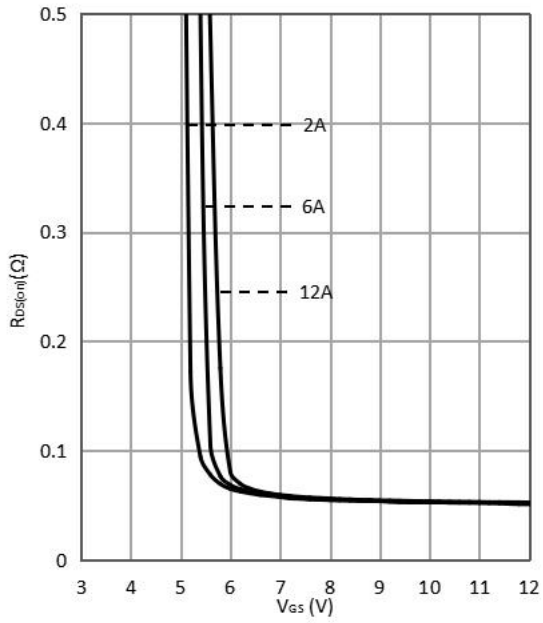
Parameter: V_{GS}

Figure 2. Typical Output Characteristics T_J=150° C



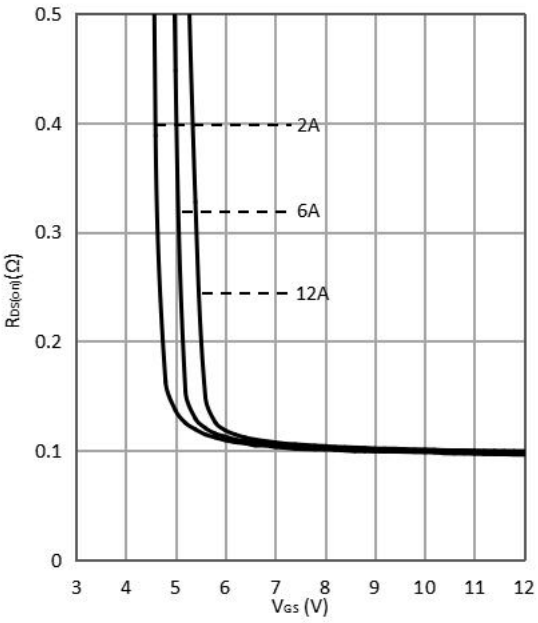
Parameter: V_{GS}

Figure 3.Typical Drain to Source On-resistance T_J= 25° C



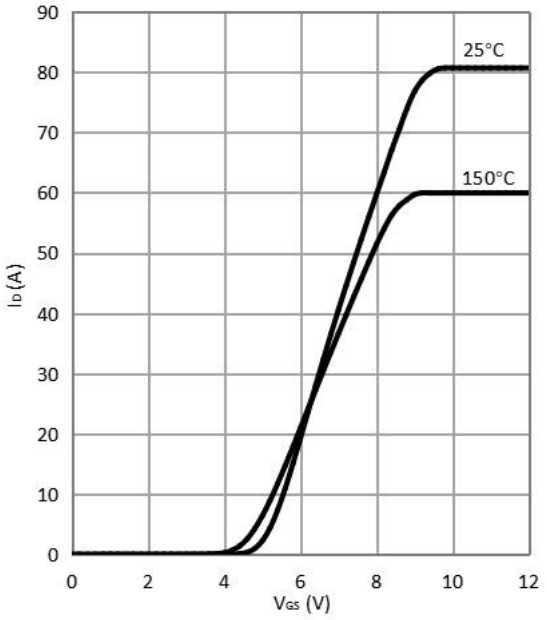
V_{DS}=10V, Parameter: T_J

Figure 4. Typical Drain to Source On-resistance T_J= 150° C



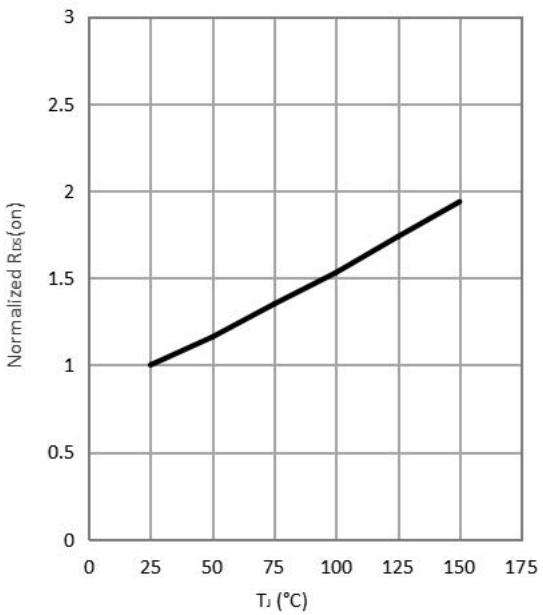
I_D=500uA

Figure 5. Typical Transfer Characteristics



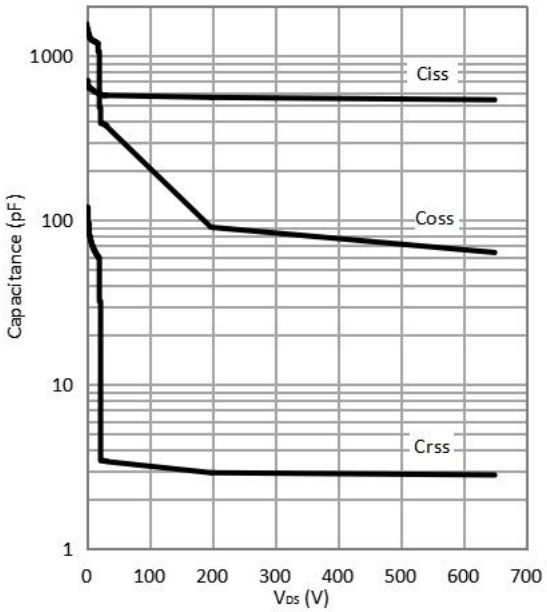
V_{DS}=10V, Parameter: T_J

Figure 6. Normalized On-resistance



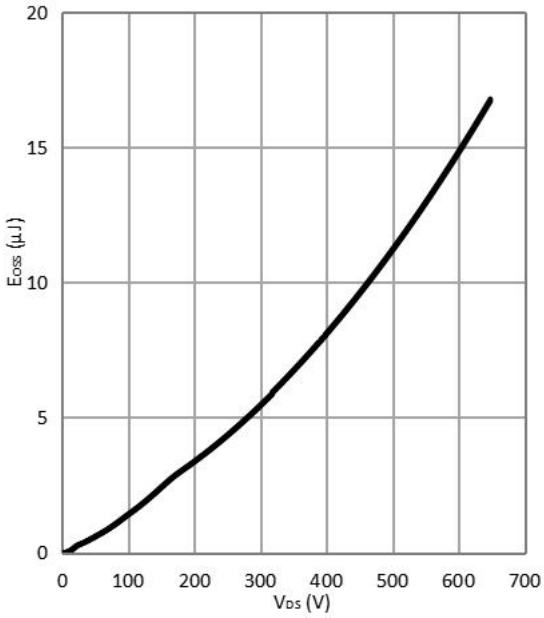
I_D=4A, V_{GS}=12V

Figure 7. Typical Capacitance



V_{GS}=0V, f=1MHz

Figure 8. Typical Coss Stored Energy



V_{GS}=0V, f=1MHz

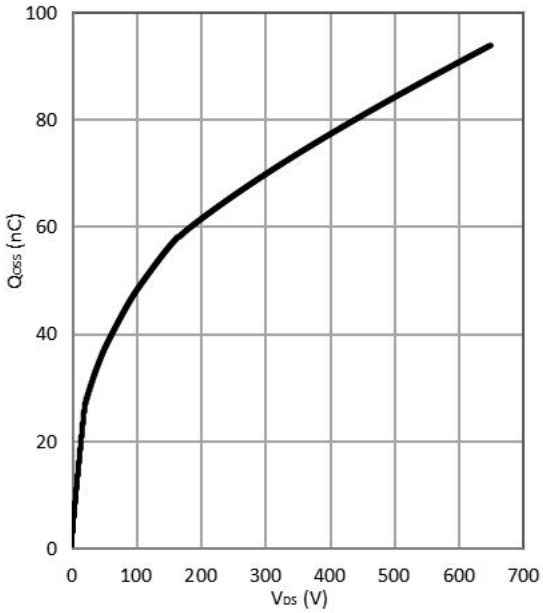
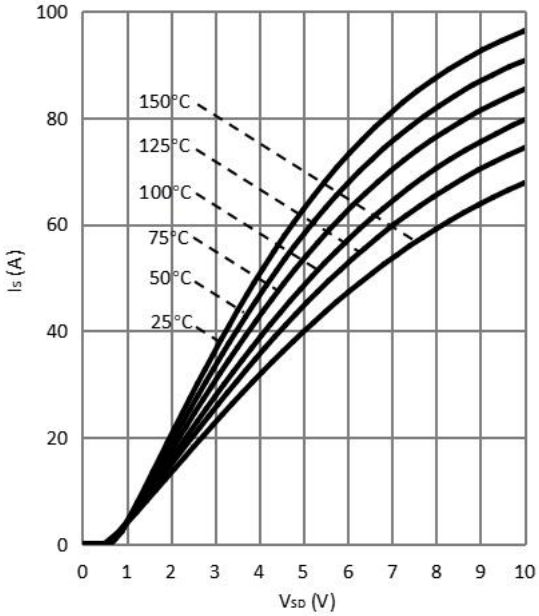
Figure 9. Typical Qoss	Figure 10. Forward Characteristic of Rev. Diode
	
V_{GS}=0V, f=1MHz	Is=f(V_{SD}), Parameter T_J

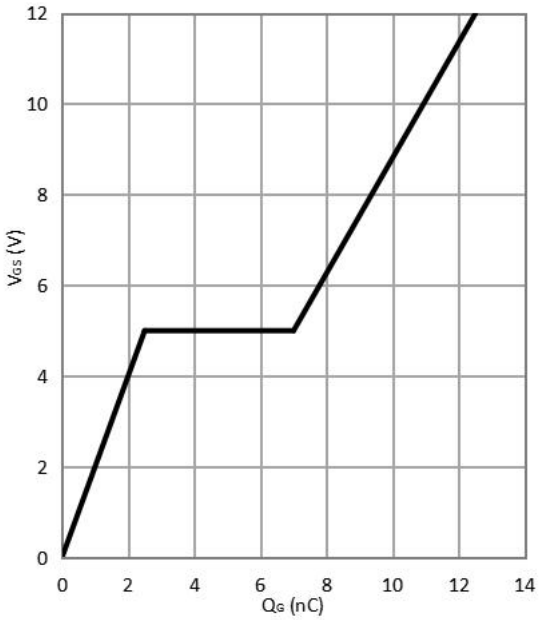
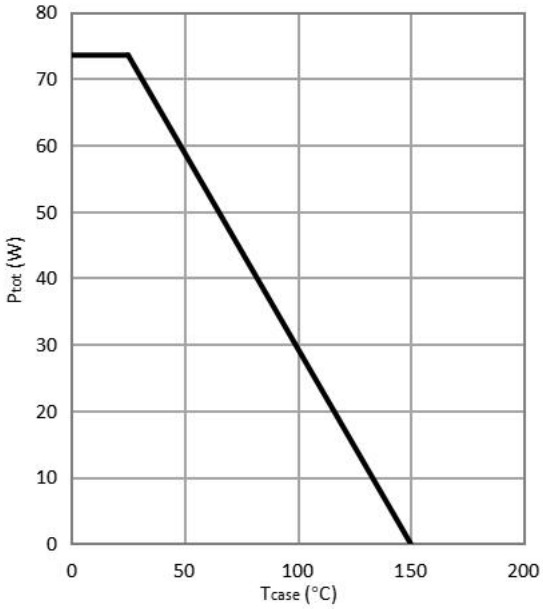
Figure 11. Typical Gate Charge	Figure 12. Power Dissipation
	
I_{DS}=14A, V_{DS}=400V	

Figure 13. Current Derating

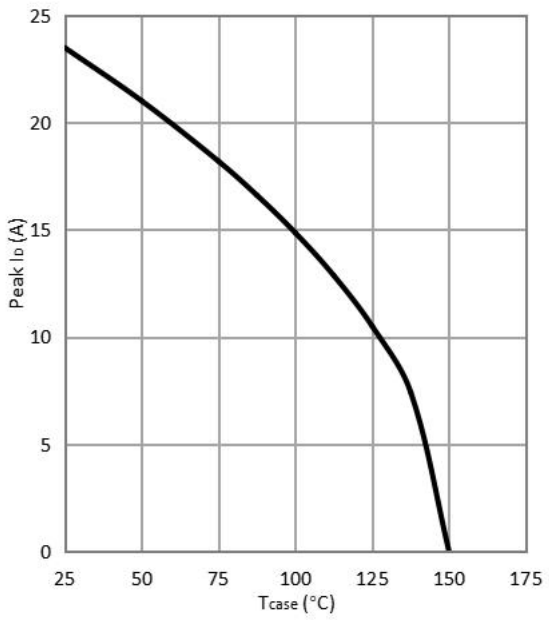


Figure 14. Transient Thermal Resistance

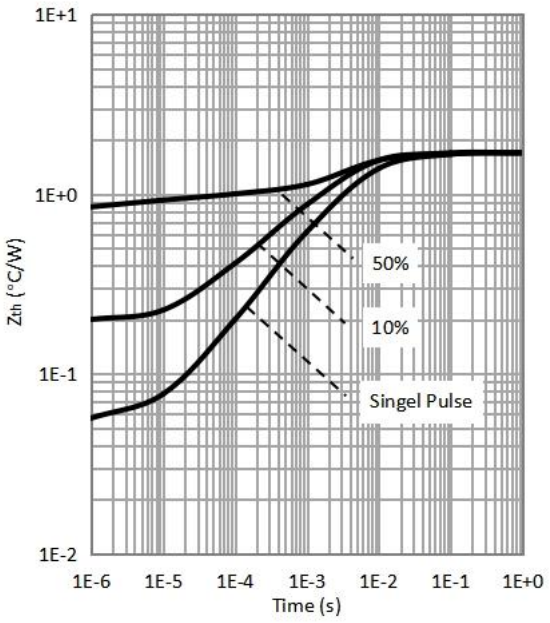
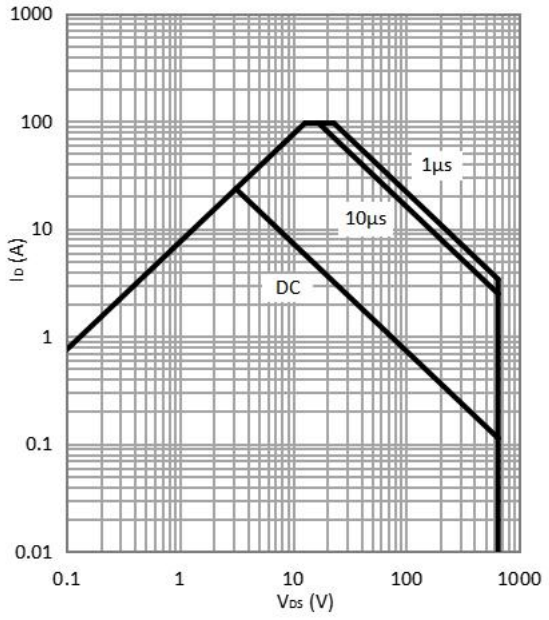
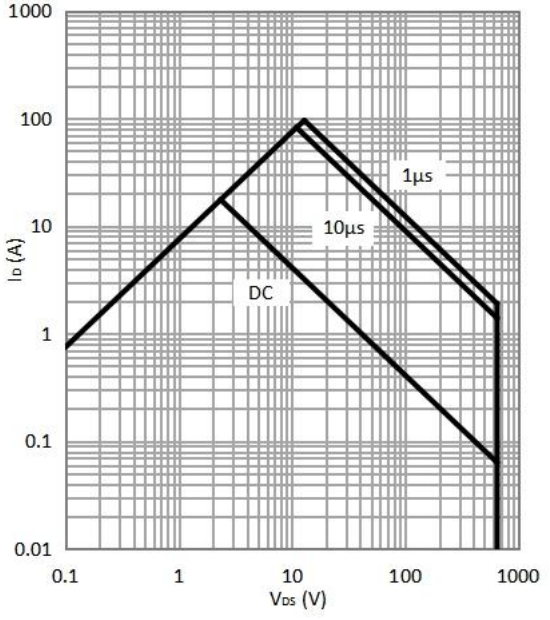


Figure 15. Safe Operating Area T_C=25° C



calculated based on thermal limit

Figure 16. Safe Operating Area T_C=80° C



calculated based on thermal limit

Test Circuits and Waveforms

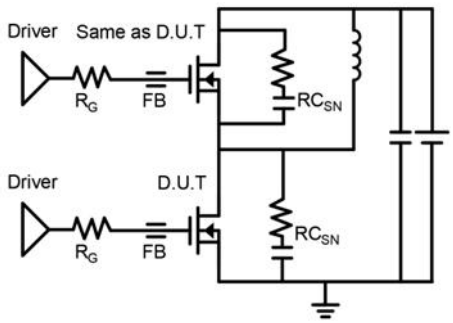
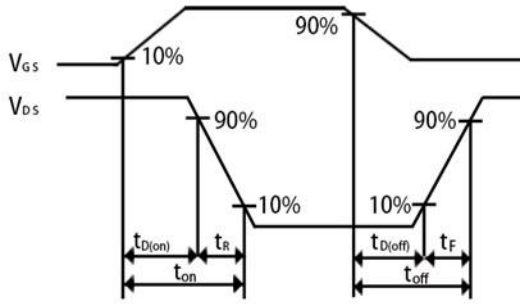
Figure 17. Switching Time Test Circuit	Figure 18. Switching Time Waveform
	

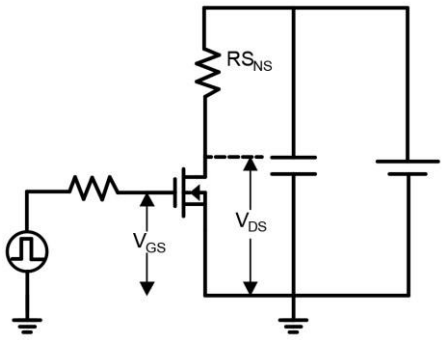
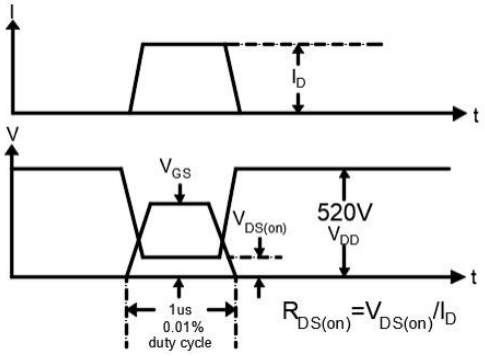
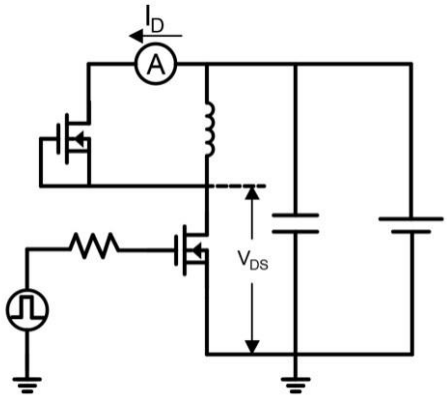
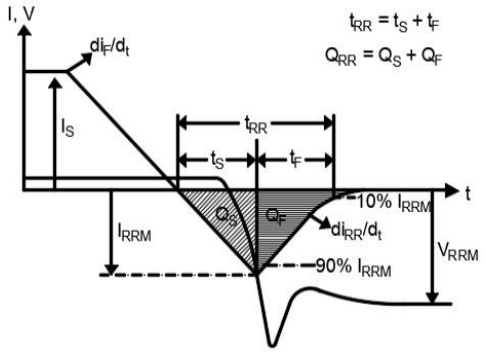
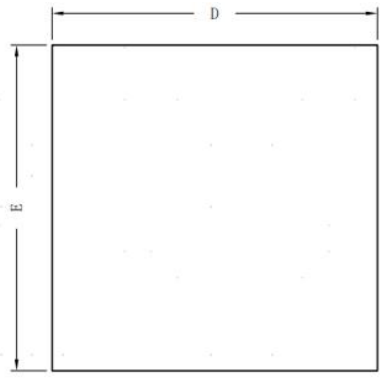
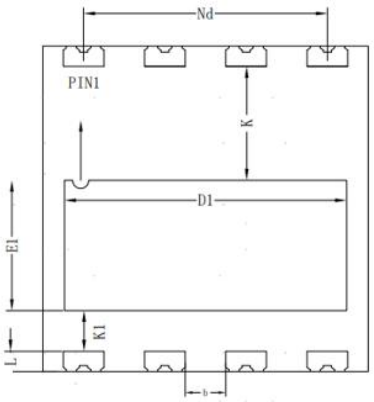
Figure 19. Dynamic $R_{DS(on)}$ Test Circuit	Figure 20. Dynamic $R_{DS(on)}$ Waveform
	

Figure 21. Diode Characteristic Test Circuits	Figure 22. Diode Recovery Waveform
	

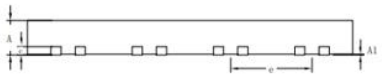
Package Outline



TOP VIEW



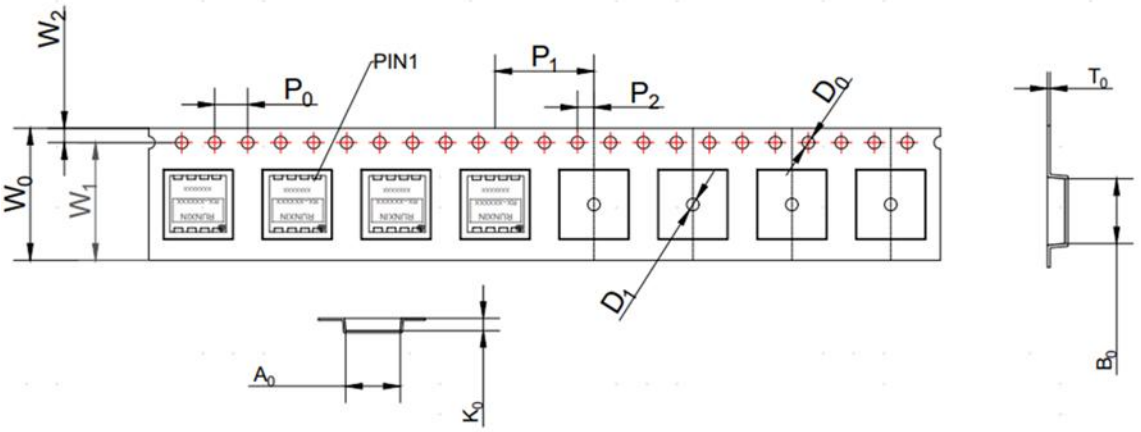
BOTTOM VIEW

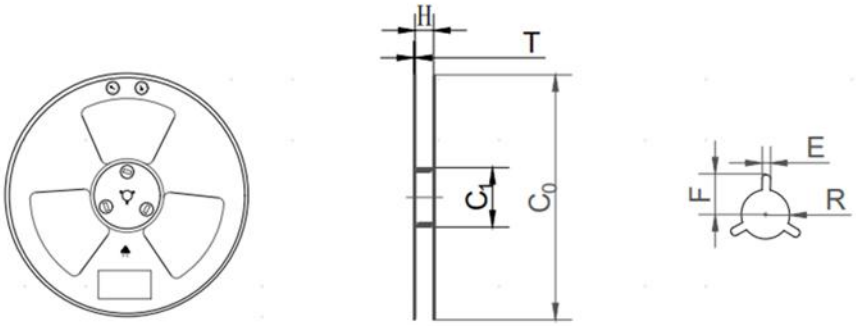


SIDE VIEW

SYMBOL	Millimeter		
	Min	Nom	Max
A	0.80	0.90	1.15
A1	0	0.02	0.05
c	—	0.20	—
b	0.90	1.00	1.10
D	7.90	8.00	8.10
D1	6.85	6.95	7.05
E	7.90	8.00	8.10
E1	3.10	3.20	3.30
e	2.00BSC		
Nd	6.00BSC		
K	2.70	2.80	2.90
K1	0.90	1.00	1.10
L	0.40	0.50	0.60

Tape and Reel Information
Dimensions are shown in millimeters





Tape Dimension(mm)					
W_0	16+0.3-0.2	P_0	4±0.1	A_0	8.3±0.1
W_1	14.25±0.1	P_1	12±0.1	B_0	8.3±0.1
W_2	1.75±0.1	P_2	2±0.1	D_1	1.5±0.25
K_0	2.7±0.1	D_0	1.5±0.1	T_0	0.3±0.05

Reel Dimension(mm)			
H	17±0.1	F	10.5±0.1
T	2±0.2	E	2.8±0.1
C_0	330±3	R	6.5±0.1
C_1	100±1		

Revision History

Version	Date	Change(s)
0.1	2025/08/28	Release preliminary datasheet

Disclaimer

Unless otherwise specified in the datasheet, the product is designed and qualified as a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.